Title (en)

PRODUCTION METHOD FOR AN ENCAPSULATED MICROMECHANICAL COMPONENT, CORRESPONDING MICROMECHANICAL COMPONENT AND ENCAPSULATION FOR A MICROMECHANICAL COMPONENT

Title (de)

HERSTELLUNGSVERFAHREN FÜR EIN VERKAPPTES MIKROMECHANISCHES BAUELEMENT, ENTSPRECHENDES MIKROMECHANISCHES BAUELEMENT UND KAPPE FÜR EIN MIKROMECHANISCHES BAUELEMENT

Title (fr)

PROCÉDÉ DE RÉALISATION D'UN COMPOSANT MICRO-MÉCANIQUE PROTÉGÉ, COMPOSANT MICRO-MÉCANIQUE CORRESPONDANT ET PROTECTION POUR COMPOSANT MICRO-MÉCANIQUE

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Application

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Abstract (en)

[origin: WO2011026699A1] The present invention provides a production method for an encapsulated micromechanical component, a corresponding micromechanical component and an encapsulation for a micromechanical component. The method has the following steps: forming an intermediate substrate (1, 1', 1''; 2, 2') with a plurality of perforations (K; K'); laminating an encapsulation substrate (KD; KD') onto a front side (VS; VS') of the intermediate substrate (1, 1', 1''; 2, 2'), which closes the perforations (K; K'') on the front side (VS; VS'), and laminating a functional MEMS wafer (3; 3') onto a rear side (RS; RS') of the intermediate substrate (1, 1', 1''; 2, 2'), the functional MEMS wafer (3; 3') being aligned with the intermediate substrate (1, 1', 1''; 2, 2') in such a way that the perforations (K; K') form respective cavities over corresponding functional regions (FB; FB') of the functional MEMS wafer (3; 3').

IPC 8 full level

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